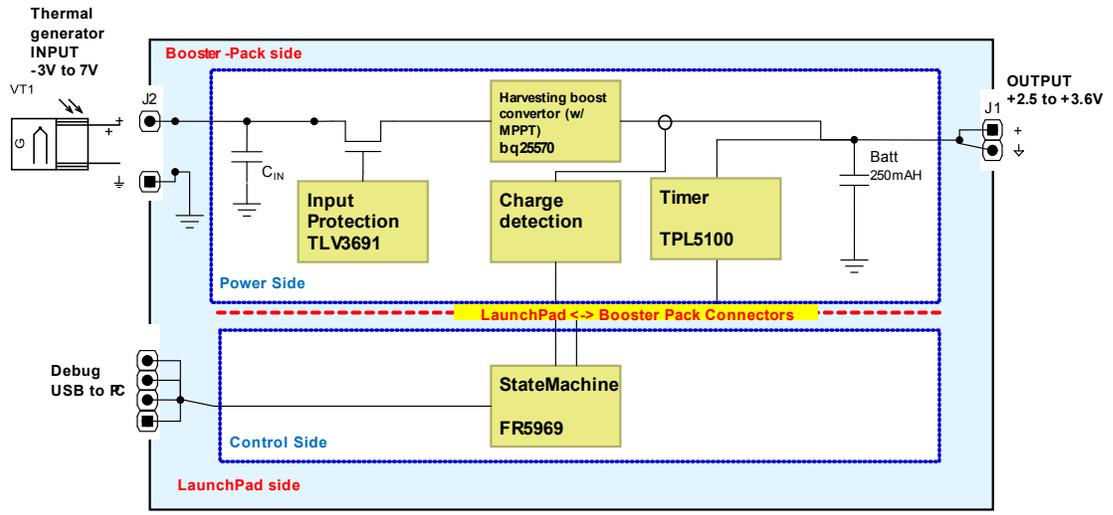


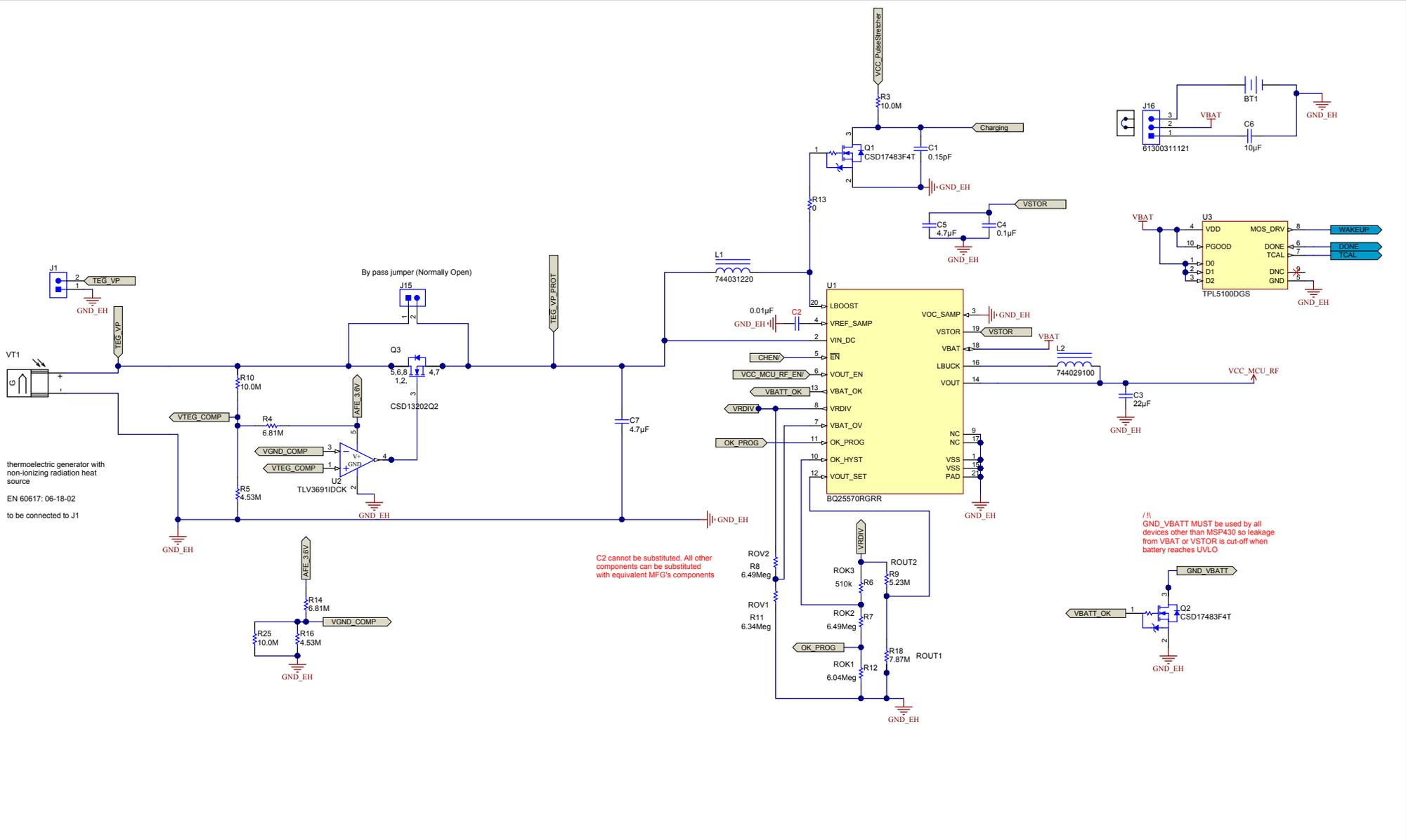
Revision History	
Revision	Notes
E1	First revision
E2	Minor tweaks



This design is intended to be used as an extension card (Booster-Pack) for LaunchPad

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TID #: TIDA-00246	Project Title: Generic Energy Harvester Adapter Module for LaunchPad		
Number: TIDA-00246	Rev: E2	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 4	
Drawn By:	File: TIDA-00246_E2_CoverSheet_SchDoc	Size: B	
Engineer: M. Chevrier	Contact: http://www.ti.com/support		



thermoelectric generator with non-ionizing radiation heat source
 EN 60617: 06-18-02
 to be connected to J1

C2 cannot be substituted. All other components can be substituted with equivalent MFG's components

/! GND_VBATT MUST be used by all devices other than MSP430 so leakage from VBAT or VSTOR is cut-off when battery reaches UVLO

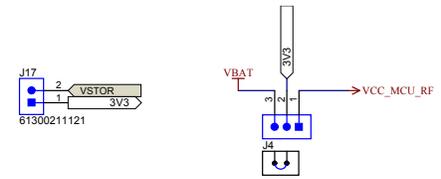
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Designed for: Public Release		Mod. Date: 3/11/2015	
Project Title: Generic Energy Harvester Adapter Module for Marlin			
Number: TIDA-00246	Rev: E2	Sheet Title:	
SVN Rev: Version control disabled		Assembly Variant: [No Variations]	Sheet: 2 of 4
Drawn By:	File: TIDA-00246_E2_Power_SchDoc	Size: B	
Engineer: M. Chevrier	Contact: http://www.ti.com/support		

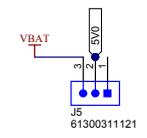


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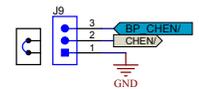
Launchpad 3V can be powered by Booster Pack:
 // Launchpad 3V must be disconnected (see UG for details)
 Vbatt : 2.5-3.6V
 VCC_MCU_RF : default set to 1.8V



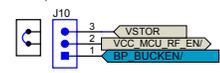
Launchpad 5V0 can be powered by Booster Pack:
 // Default EVM settings need to be changed for this to work



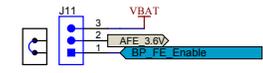
Shunt by default between 2&1 so bq25570 is enabled, alternative option is GPIO control from MCU (Launchpad)



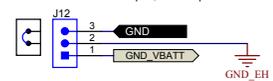
Shunt by default between 2&3 so VCC_MCU is available (Connect to VSTOR to enable the buck converter), alternative option is GPIO control from MCU



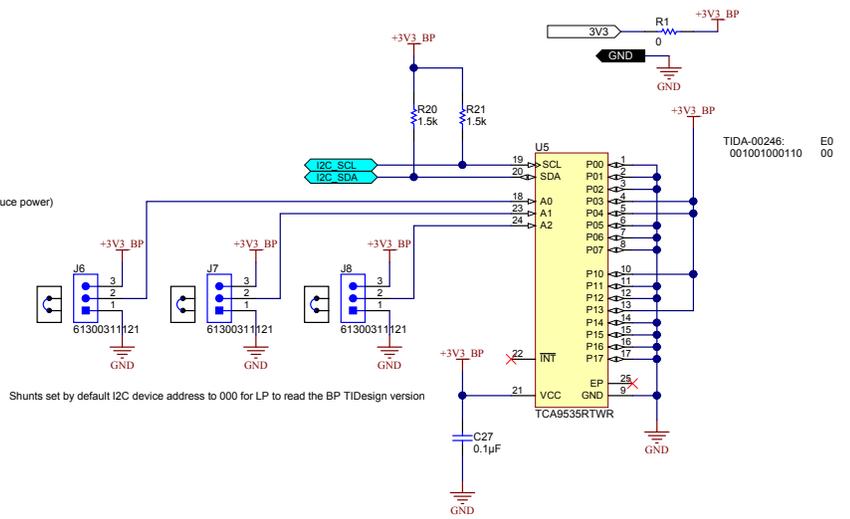
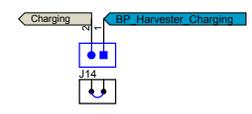
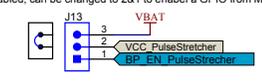
Jumpers to measure power conso of the FE protection + allow GPIO control



GND_VBATT should be used for devices other than MSP430 from the Launchpad, this is a provision for future usage and for testing

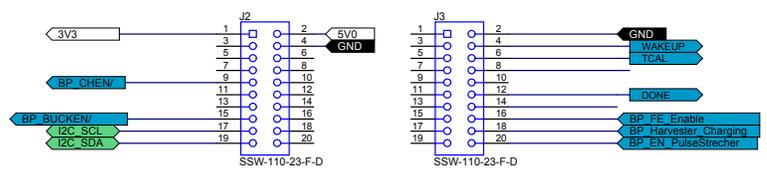


Shunt by default between 2&3 so Charge Detection is enabled, can be changed to 2&1 to enable a GPIO from MCU (Launchpad) to control it (and reduce power)



TIDA-00246: E0
 001001000110 00

Shunts set by default I2C device address to 000 for LP to read the BP TIDesign version



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Number: TIDA-00246	Rev: E2	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 4
Drawn By:	File: TIDA-00246_E2_BoosterPack_SchDoc	Size: B
Engineer: M. Chevrier	Contact: http://www.ti.com/support	



1 2 3 4 5 6

A

A



PCB Number: TIDA-00246
PCB Rev: E2

PCB LOGO
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PCB LOGO
Pb-Free Symbol

PCB LOGO
CAUTION. READ USER GUIDE BEFORE USE

B

B

C

C

ZZ1
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

ZZ2
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

ZZ3
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

D

D

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TID #: TIDA-00246	Project Title: Generic Energy Harvester Adapter Module for Maric		
Number: TIDA-00246 Rev: E2	Sheet Title:		
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 4 of 4	
Drawn By:	File: TIDA-00246_E2_TID_Hardware.SchDoc	Size: B	
Engineer: M. Chevrier	Contact: http://www.ti.com/support		

1 2 3 4 5 6

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